



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-01-30
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FB6P*0922BS6	A	ZY1A	2018-01-30
Amount	UoM	Unit type	ST ECOPACK Grade	
34.89	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.4x3x0.9	8	gull wing	
Comment	Package: 6P TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid for TS922IYPT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	FB6P*0922B56					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.322	mg	supplier	die	Silicon (Si)	7440-21-3		1.311	mg	991679	37575
Die			mg	supplier	metallization	Aluminum (Al)	7429-90-5		0.005	mg	3782	143
Die			mg	supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.003	mg	2269	86
Die			mg	supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.003	mg	2269	86
Leadframe	Copper and its alloy	15.868	mg	supplier	alloy	Copper (Cu)	7440-50-8		14.981	mg	944101	429378
Leadframe			mg	supplier	alloy	Iron (Fe)	7439-89-6		0.361	mg	22750	10347
Leadframe			mg	supplier	alloy	Zinc (Zn)	7440-66-6		0.018	mg	1134	516
Leadframe			mg	supplier	alloy	Phosphorus (P)	12185-10-3		0.005	mg	315	143
Leadframe			mg	supplier	metallization	Silver(Ag)	7440-22-4		0.503	mg	31699	14417
Die attach	Other organic materials	0.336	mg	supplier	glue	Epoxy resin A	9003-36-5		0.024	mg	73429	688
Die attach			mg	supplier	glue	Iron (Fe)	7439-89-6		0.014	mg	41667	401
Die attach			mg	supplier	glue	Silver(Ag)	7440-22-4		0.256	mg	761905	7337
Die attach			mg	supplier	glue	Iron Phosphide (Fe2P)	1310-43-6		0.014	mg	41667	401
Die attach			mg	supplier	glue	Polyoxypropylenediamine	9046-10-0		0.014	mg	41667	401
Die attach			mg	supplier	glue	2,6-Diglycidyl phenyl allyl ether oligomer	EC 417-470-1		0.014	mg	41667	401
Bonding wire	Precious metals	0.138	mg	supplier	wire	Gold (Au)	7440-57-5		0.138	mg	1000000	3955
Encapsulation	Other inorganic materials	16.351	mg	supplier	molding compound	Epoxy Resin	29690-82-2		1.227	mg	75041	35168
Encapsulation			mg	supplier	molding compound	Silica fused (SiO2)	60676-86-0		14.387	mg	879885	412353
Encapsulation			mg	supplier	molding compound	Carbon Black	1333-86-4		0.083	mg	5076	2379
Encapsulation			mg	supplier	molding compound	Phenol Resin	25068-38-6		0.654	mg	39998	18745
Finishing	Other inorganic materials	0.873	mg	supplier	connection coating	Tin (Sn)	7440-31-5		0.873	mg	1000000	25021